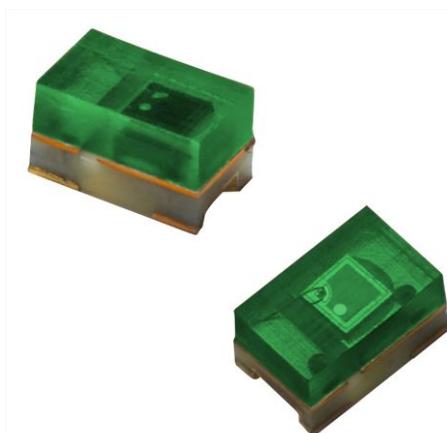


Ambient Light Sensor in 0805 Package



FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- High photo sensitivity
- Adapted to human eye responsivity
- Supression filter for near infrared radiation
- Angle of half sensitivity: $\phi = \pm 60^\circ$
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912




RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

DESCRIPTION

TEMT6200FX01 ambient light sensor is a silicon NPN epitaxial planar phototransistor in a miniature transparent 0805 package for surface mounting. It is sensitive to visible light much like the human eye and has peak sensitivity at 550 nm.

APPLICATIONS

- Automotive sensors
- Ambient light sensor for display backlight dimming in:
 - Mobile phones
 - Notebook computers
 - PDAs
 - Cameras
 - Dashboards

PRODUCT SUMMARY

COMPONENT	I_{PCE} (μ A)	ϕ (deg)	$\lambda_{0.5}$ (nm)
TEMT6200FX01	23	± 60	450 to 610

Note

- Test condition see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TEMT6200FX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel. Label with I_{PCE} group on each reel. Specifications of group A/B/C see table "Type Dedicated Characteristics"	0805

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ C$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Collector emitter voltage		V_{CEO}	6	V
Emitter collector voltage		V_{ECO}	1.5	V
Collector current		I_C	20	mA
Power dissipation		P_V	100	mW
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	-40 to +100	°C
Storage temperature range		T_{stg}	-40 to +100	°C
Soldering temperature	Acc. reflow profile fig. 9	T_{sd}	260	°C
Thermal resistance junction/ambient	Soldered on PCB with pad dimensions: 4 mm x 4 mm	R_{thJA}	450	K/W

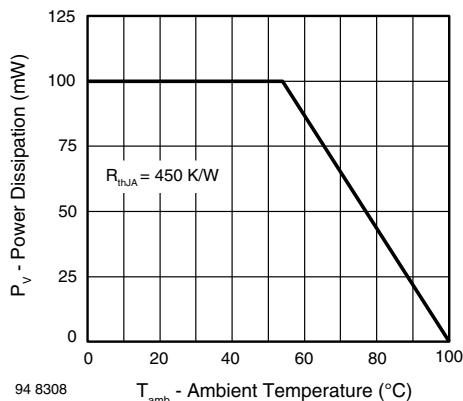


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25$ °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Collector emitter breakdown voltage	$I_C = 0.1$ mA	V_{CEO}	6			V
Collector dark current	$V_{CE} = 5$ V, $E = 0$ lx	I_{CEO}		3	50	nA
Collector emitter capacitance	$V_{CE} = 0$ V, $f = 1$ MHz, $E = 0$ lx	C_{CEO}		16		pF
Photo current	$E_V = 20$ lx, CIE illuminant A, $V_{CE} = 5$ V	I_{PCE}		4.6		µA
	$E_V = 100$ lx, CIE illuminant A, $V_{CE} = 5$ V	I_{PCE}	7.5	23	39	µA
Temperature coefficient of I_{PCE}	CIE illuminant A	TK_{IPCE}		1.18		%/K
	LED, white	TK_{IPCE}		0.9		%/K
Angle of half sensitivity		φ		± 60		deg
Wavelength of peak sensitivity		λ_p		550		nm
Range of spectral bandwidth		$\lambda_{0.5}$	450 to 610			nm
Collector emitter saturation voltage	$E_V = 20$ lx, 0.45 µA	V_{CEsat}		0.1		V

TYPE DEDICATED CHARACTERISTICS ($T_{amb} = 25$ °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	BINNED GROUP	SYMBOL	MIN.	MAX.	UNIT
Photo current	$E_V = 100$ lx, CIE illuminant A, $V_{CETz51} = 5$ V	A	I_{PCE}	7.5	15	µA
		B	I_{PCE}	12	24	µA
		C	I_{PCE}	19.5	39	µA

Note

- Each 3000 piece packing unit will contain a single group. The label on the bag will indicate which binned group is in the bag. A specific group cannot be ordered. Production shipments containing multiple bags will likely include multiple groups. Please design accordingly.

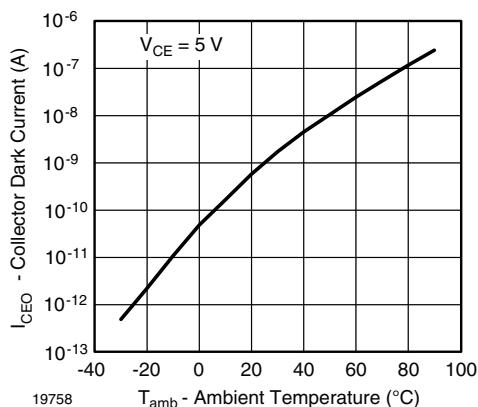
BASIC CHARACTERISTICS ($T_{amb} = 25$ °C, unless otherwise specified)


Fig. 2 - Collector Dark Current vs. Ambient Temperature

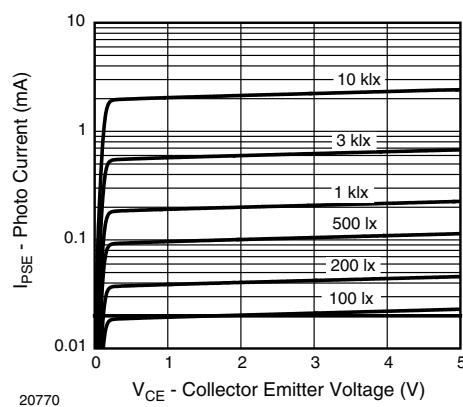


Fig. 5 - Photo Current vs. Collector Emitter Voltage

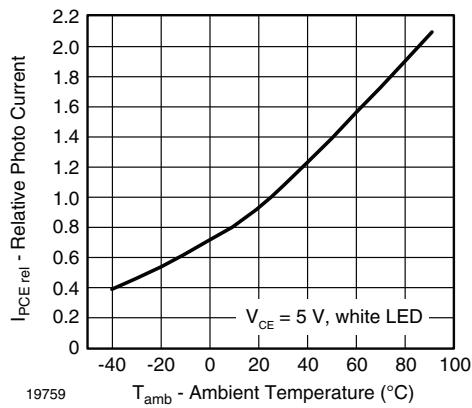


Fig. 3 - Relative Photo Current vs. Ambient Temperature

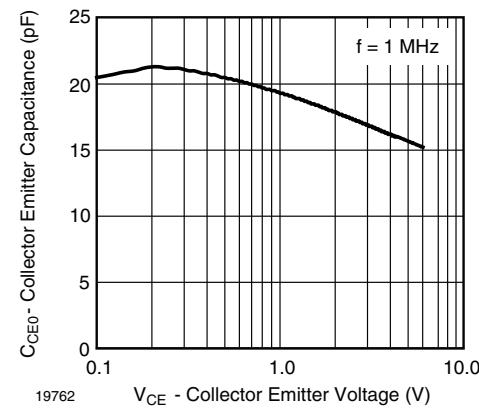


Fig. 6 - Collector Emitter Capacitance vs. Collector Emitter Voltage

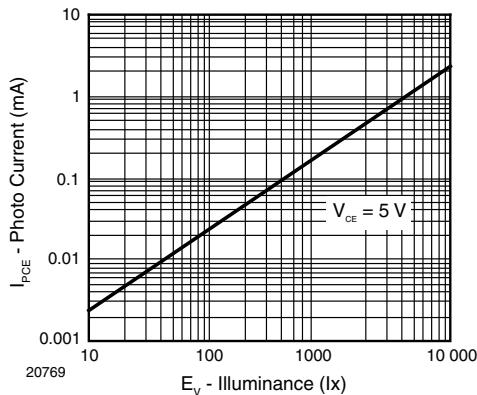


Fig. 4 - Photo Current vs. Illuminance

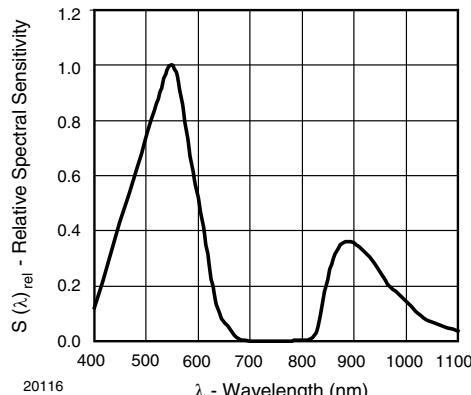


Fig. 7 - Relative Spectral Sensitivity vs. Wavelength

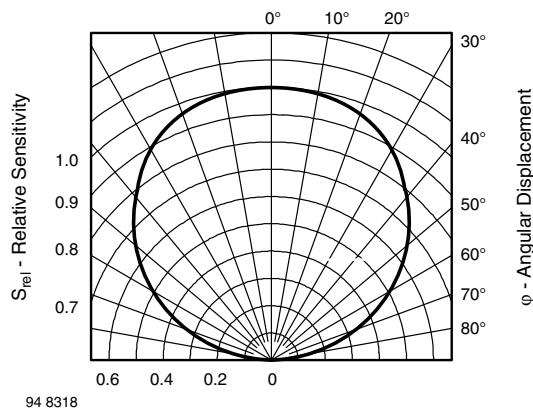


Fig. 8 - Relative Radiant Sensitivity vs. Angular Displacement

REFLOW SOLDER PROFILE

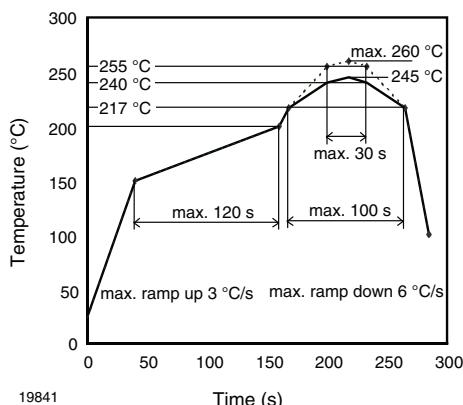


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

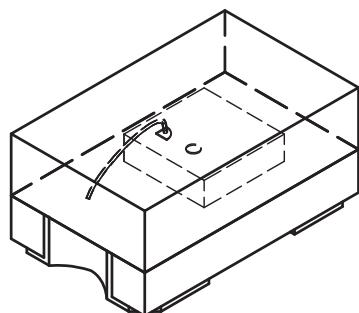
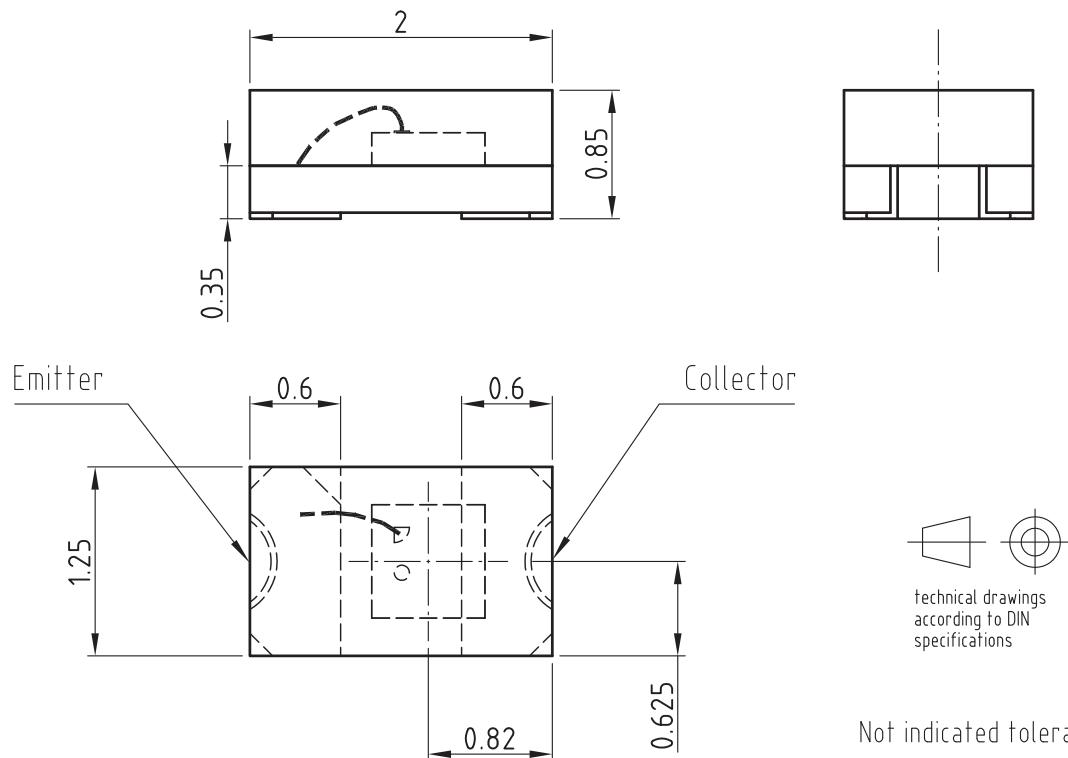
Moisture sensitivity: level 3

Floor life: 168 h

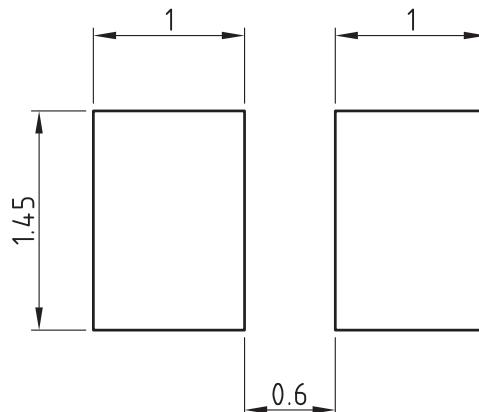
Conditions: $T_{amb} < 30^{\circ}\text{C}$, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40°C ($\pm 5^{\circ}\text{C}$), RH < 5 %.

PACKAGE DIMENSIONS in millimeters


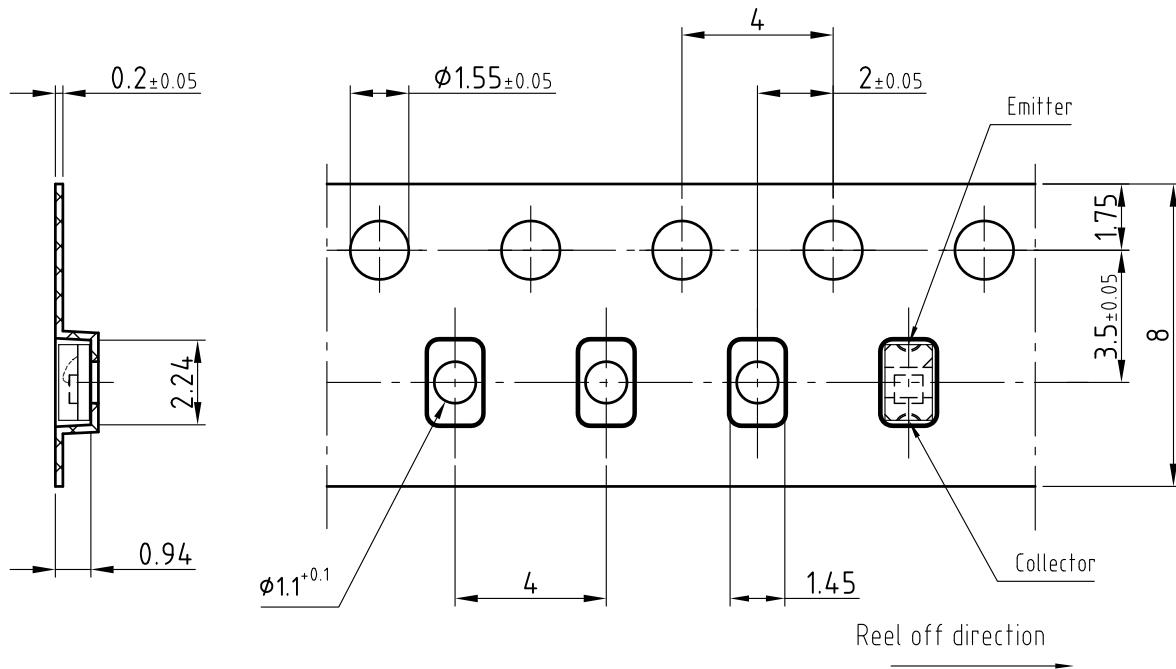
Recommended solder pad
Footprint



Drawing-No.: 6.541-5063.01-4

Issue: 3; 23.02.07

19757

BLISTER TAPE DIMENSIONS in millimeters


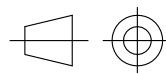
Drawing-No.: 9.700-5310.01-4

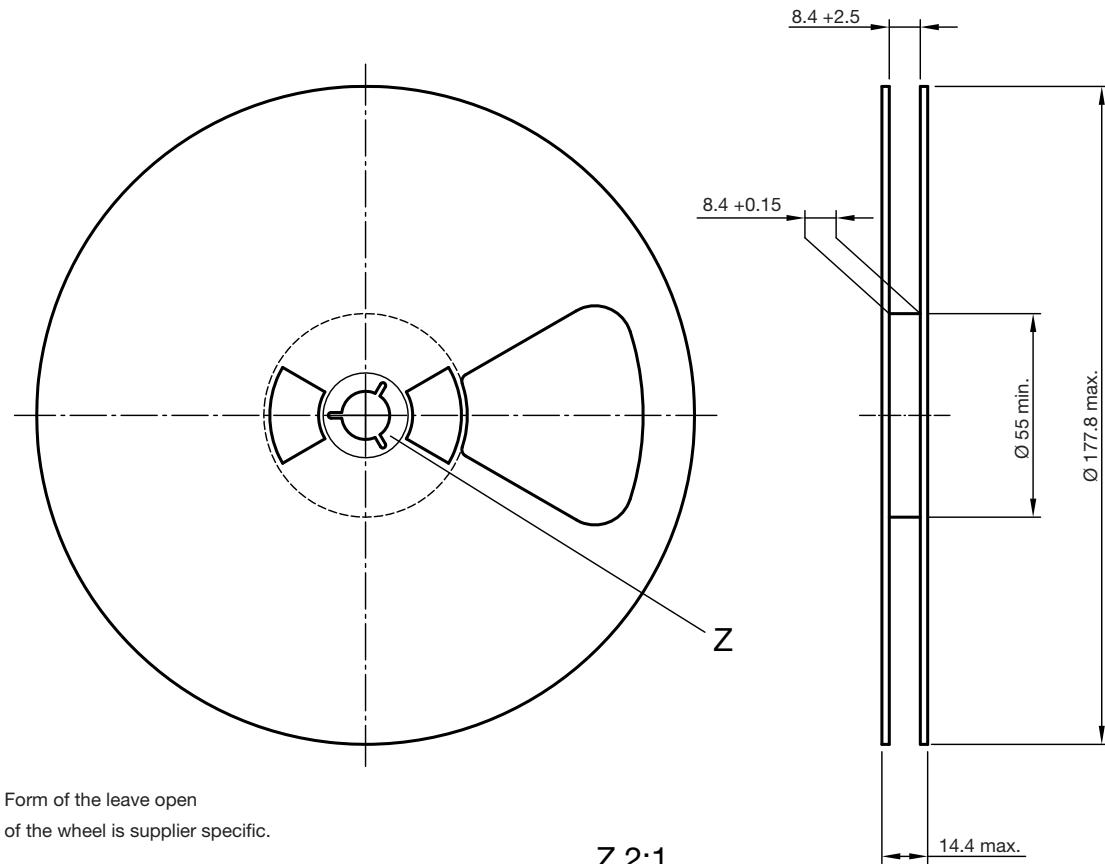
Issue: 2; 14.08.07

20690

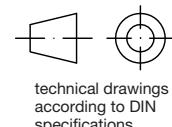
Not indicated tolerances ±0.1

Quantity per reel: 3000 pcs


technical drawings
according to DIN
specifications

REEL DIMENSIONS in millimeters


Drawing-No.: 9.800-5096.01-4
Issue: 2; 26.04.10
20875



technical drawings according to DIN specifications

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